

RELIABILITY REPORT
FOR
MAX1137EUA+T
PLASTIC ENCAPSULATED DEVICES

March 30, 2012

MAXIM INTEGRATED PRODUCTS

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Conclusion

The MAX1137EUA+T successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

Table of Contents

I.Device Description	IV.Die Information
II.Manufacturing Information	V.Quality Assurance Information
III.Packaging Information	VI.Reliability Evaluation
.....Attachments	

I. Device Description

A. General

The MAX1136-MAX1139 low-power, 10-bit, multichannel analog-to-digital converters (ADCs) feature internal track/hold (T/H), voltage reference, clock, and an I²C-compatible 2-wire serial interface. These devices operate from a single supply of 2.7V to 3.6V (MAX1137/MAX1139) or 4.5V to 5.5V (MAX1136/MAX1138) and require only 670 μ A at the maximum sampling rate of 94.4ksps. Supply current falls below 230 μ A for sampling rates under 46ksps. AutoShutdown(tm) powers down the devices between conversions, reducing supply current to less than 1 μ A at low throughput rates. The MAX1136/MAX1137 have four analog input channels each, while the MAX1138/MAX1139 have 12 analog input channels each. The fully differential analog inputs are software configurable for unipolar or bipolar, and single ended or differential operation. The full-scale analog input range is determined by the internal reference or by an externally applied reference voltage ranging from 1V to VDD. The MAX1137/MAX1139 feature a 2.048V internal reference and the MAX1136/MAX1138 feature a 4.096V internal reference. The MAX1136/MAX1137 are available in an 8-pin μ MAX[®] package. The MAX1138/MAX1139 are available in a 16-pin QSOP package. The MAX1136-MAX1139 are guaranteed over the extended temperature range (-40°C to +85°C). For pin-compatible 12-bit parts, refer to the MAX1236-MAX1239 data sheet. For pin-compatible 8-bit parts, refer to the MAX1036-MAX1039 data sheet.

II. Manufacturing Information

A. Description/Function:	2.7V to 3.6V and 4.5V to 5.5V, Low-Power, 4-/12-Channel, 2-Wire Serial 10-Bit ADCs
B. Process:	C6
C. Number of Device Transistors:	12033
D. Fabrication Location:	Japan
E. Assembly Location:	Thailand
F. Date of Initial Production:	April 27, 2002

III. Packaging Information

A. Package Type:	3x3 mm 8L UMAX
B. Lead Frame:	EFTEC64T
C. Lead Finish:	NICKEL-PALLADIUM
D. Die Attach:	Non-conductive
E. Bondwire:	Au (1 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-9000-3523 / B
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	1
J. Single Layer Theta Ja:	170°C/W
K. Single Layer Theta Jc:	8°C/W
L. Multi Layer Theta Ja:	170°C/W
M. Multi Layer Theta Jc:	8°C/W

IV. Die Information

A. Dimensions:	75 X 88 mils
B. Passivation:	Si ₃ N ₄ /SiO ₂ (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/0.5%Cu with Ti/TiN Barrier
D. Backside Metallization:	None
E. Minimum Metal Width:	0.6 microns (as drawn)
F. Minimum Metal Spacing:	0.6 microns (as drawn)
G. Bondpad Dimensions:	
H. Isolation Dielectric:	SiO ₂
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

- A. Quality Assurance Contacts: Richard Aburano (Manager, Reliability Engineering)
Don Lipps (Manager, Reliability Engineering)
Bryan Preeshl (Vice President of QA)
- B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.
0.1% For all Visual Defects.
- C. Observed Outgoing Defect Rate: < 50 ppm
- D. Sampling Plan: Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4340 \times 138 \times 2} \quad (\text{Chi square value for MTTF upper limit})$$

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$$\lambda = 7.9 \times 10^{-9}$$

$$\lambda = 7.9 \text{ F.I.T. (60\% confidence level @ 25}^\circ\text{C)}$$

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at <http://www.maxim-ic.com/qa/reliability/monitor>. Cumulative monitor data for the C6 Process results in a FIT Rate of 0.43 @ 25C and 7.50 @ 55C (0.8 eV, 60% UCL)

B. E.S.D. and Latch-Up Testing (Latch-up lot E2B3GA004B D/C 0908)

The AC30-3 die type has been found to have all pins able to withstand a HBM transient pulse of pulse of:

ESD-HBM:	+/- 2500V per JEDEC JESD22-A114	Lot E2B3GA004B, D/C 0908
ESD-MM:	+/- 200V per JEDEC JESD22-A115	Lot SHS4AQ001B, D/C 0650

Latch-Up testing has shown that this device withstands a current of +/- 250mA and overvoltage per JEDEC JESD78.

Table 1
Reliability Evaluation Test Results

MAX1137EUA+T

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES	COMMENTS
Static Life Test (Note 1)	Ta = 135°C	DC Parameters	48	0	E2B6EA007B, D/C 0951
	Biased	& functionality	45	0	S2B1FQ001B, D/C 0538
	Time = 192 hrs.		45	0	I2B3DA010A, D/C 0345

Note 1: Life Test Data may represent plastic DIP qualification lots.